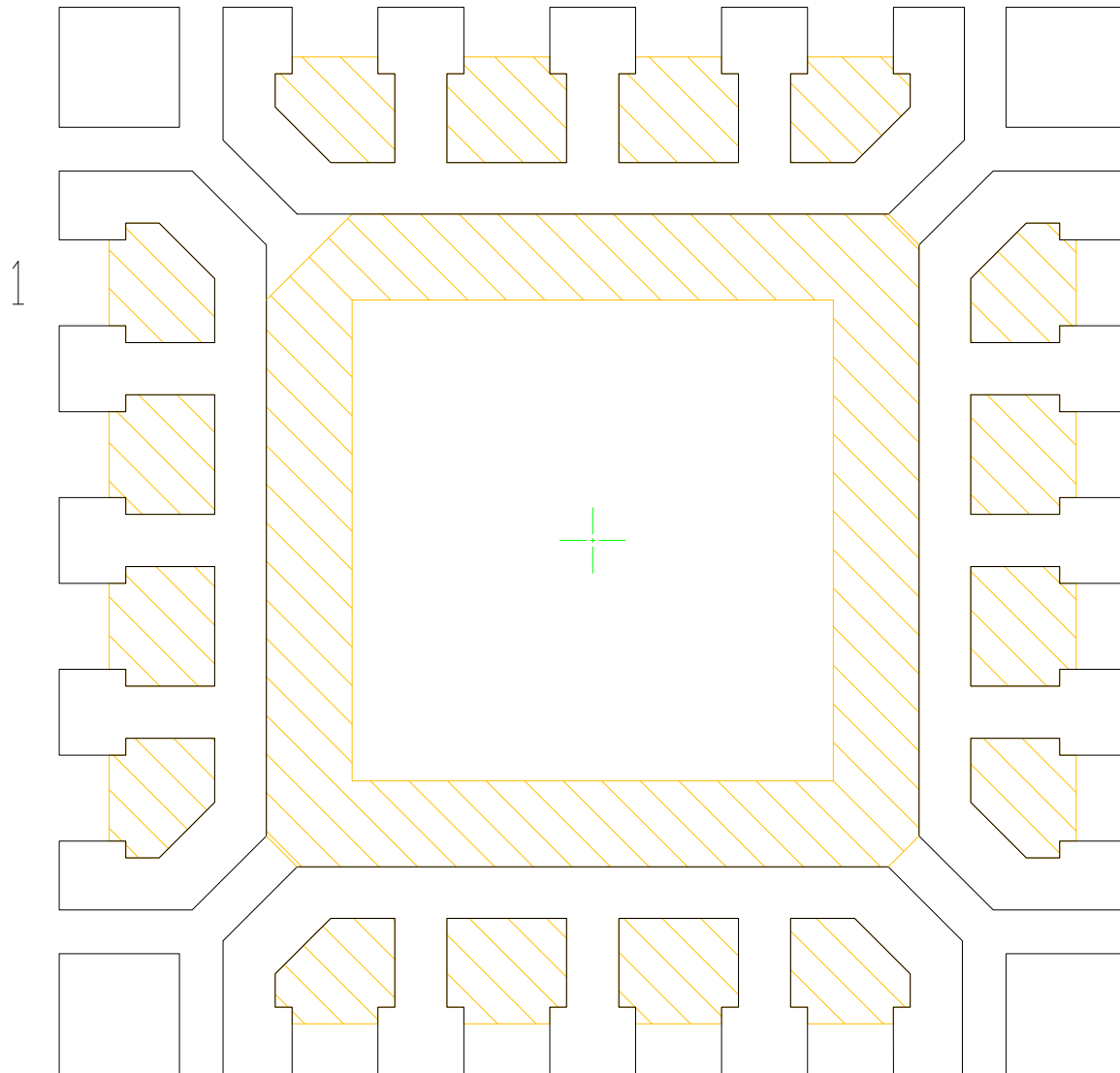



REVISIONS		
REV	DESCRIPTION	DATE
C	INCREASED DAP SIZE, REDUCED GROUND RING WIDTH	07/24/17



 NiPdAu PLATING

ALL INFORMATION CONTAINED HEREIN IS THE PROPERTY OF PROMEX, INC. AND IS CONSIDERED PROPRIETARY AND SUBJECT TO RETURN UPON DEMAND. ACCEPTANCE AND RETENTION HEREOF SIGNIFIES AGREEMENT BY THE RECIPIENT THAT THE INFORMATION WILL NOT BE DISCLOSED TO OTHERS NOR USED CONTRARY TO THE INTEREST OF PROMEX, INC. WITHOUT PRIOR WRITTEN PERMISSION.

CUSTOMER: xxxxx	DOCUMENT #:	 <a href="http://www.promex-ind.com">www.promex-ind.com</a>	
PROJECT NAME: xxxxx	DIE ATTACH PAD SIZE: 1.90 x 1.90 mm		
DIE SIZE, mm: xxxxx	EXPOSED PAD SIZE: 1.65 x 1.65 mm	TITLE	
DIE THICKNESS, um: xxxxx	DAP PLATING OPTION: GROUND RING	QFN 16L 3x3 mm 0.50 PITCH BOND SHELL	
BOND PAD PITCH, um: xxxxx	PLATING MATERIAL: NiPdAu	LEADFRAME P/N:	REV
BOND PAD OPENING, um: xxxxx	LEADFRAME MATERIAL: C194 FH	235-00050	00
WIRE SIZE, um: xxxxx	LEADFRAME THICKNESS: 0.203±0.0075 mm	DO NOT SCALE	FILE NAME
			16L-QFN-3X3-50P-BD.DWG
			SHEET
			1 OF 1